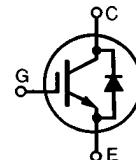
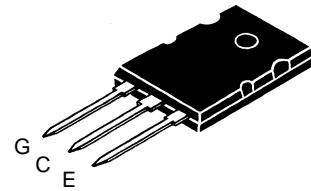


**HiPerFAST™**  
**IGBT with Diode**
**Combi Pack**
**IXGK 50N60AU1**
 $V_{CES}$  = 600 V  
 $I_{C25}$  = 75 A  
 $V_{CE(sat)}$  = 2.7 V  
 $t_{fi}$  = 275 ns


Symbol	Test Conditions	Maximum Ratings		
$V_{CES}$	$T_J$ = 25°C to 150°C	600	V	
$V_{CGR}$	$T_J$ = 25°C to 150°C; $R_{GE}$ = 1 MΩ	600	V	
$V_{GES}$	Continuous	±20	V	
$V_{GEM}$	Transient	±30	V	
$I_{C25}$	$T_c$ = 25°C, limited by leads	75	A	
$I_{C90}$	$T_c$ = 90°C	50	A	
$I_{CM}$	$T_c$ = 25°C, 1 ms	200	A	
<b>SSOA (RBSOA)</b>	$V_{GE} = 15$ V, $T_{VJ} = 125$ °C, $R_G = 10$ Ω Clamped inductive load, $L = 30$ μH	$I_{CM} = 100$ A @ 0.8 $V_{CES}$		
$P_c$	$T_c$ = 25°C	300	W	
$T_J$		-55 ... +150	°C	
$T_{JM}$		150	°C	
$T_{stg}$		-55 ... +150	°C	
$M_d$	Mounting torque (M4)	0.9/6	Nm/lb.in.	
<b>Weight</b>		10	g	
Maximum lead temperature for soldering 1.6 mm (0.062 in.) from case for 10 s		300	°C	

**TO-264 AA**


G = Gate,  
E = Emitter,  
C = Collector,  
TAB = Collector

**Features**

- International standard package JEDEC TO-264 AA
- High frequency IGBT and anti-parallel FRED in one package
- 2nd generation HDMOS™ process
- Low  $V_{CE(sat)}$ 
  - for minimum on-state conduction losses
- MOS Gate turn-on
  - drive simplicity
- Fast Recovery Epitaxial Diode (FRED)
  - soft recovery with low  $I_{RM}$

**Applications**

- AC motor speed control
- DC servo and robot drives
- DC choppers
- Uninterruptible power supplies (UPS)
- Switch-mode and resonant-mode power supplies

**Advantages**

- Space savings (two devices in one package)
- Easy to mount with 1 screw (isolated mounting screw hole)
- Reduces assembly time and cost
- High power density

Symbol	Test Conditions	Characteristic Values		
		( $T_J$ = 25°C, unless otherwise specified)	min.	typ.
$BV_{CES}$	$I_c$ = 500 μA, $V_{GE}$ = 0 V	600		V
$V_{GE(th)}$	$I_c$ = 500 μA, $V_{CE} = V_{GE}$	2.5		5.5 V
$I_{CES}$	$V_{CE} = 0.8 \cdot V_{CES}$ $V_{GE} = 0$ V	$T_J = 25$ °C $T_J = 125$ °C		250 μA 15 mA
$I_{GES}$	$V_{CE} = 0$ V, $V_{GE} = \pm 20$ V			±100 nA
$V_{CE(sat)}$	$I_c = I_{C90}$ , $V_{GE} = 15$ V			2.7 V

Symbol	Test Conditions	Characteristic Values			
		( $T_J = 25^\circ\text{C}$ , unless otherwise specified)	min.	typ.	max.
$g_{fs}$	$I_C = I_{C90}$ ; $V_{CE} = 10 \text{ V}$ , Pulse test, $t \leq 300 \mu\text{s}$ , duty cycle $\leq 2\%$	25	35	S	
$Q_g$ $Q_{ge}$ $Q_{gc}$	$I_C = I_{C90}$ , $V_{GE} = 15 \text{ V}$ , $V_{CE} = 0.5 V_{CES}$	200	nC		
		50	nC		
		80	nC		
$t_{d(on)}$	<b>Inductive load, <math>T_J = 25^\circ\text{C}</math></b>  $I_C = I_{C90}$ , $V_{GE} = 15 \text{ V}$ , $L = 100 \mu\text{H}$ , $V_{CE} = 0.8 V_{CES}$ , $R_G = R_{off} = 2.7 \Omega$  Remarks: Switching times may increase for $V_{CE}$ (Clamp) $> 0.8 \cdot V_{CES}$ , higher $T_J$ or increased $R_G$	50	ns		
$t_{ri}$		210	ns		
$t_{d(off)}$		200	ns		
$t_{fi}$		275	400	ns	
$E_{off}$		4.8	mJ		
$t_{d(on)}$	<b>Inductive load, <math>T_J = 125^\circ\text{C}</math></b>  $I_C = I_{C90}$ , $V_{GE} = 15 \text{ V}$ , $L = 100 \mu\text{H}$ $V_{CE} = 0.8 V_{CES}$ , $R_G = R_{off} = 2.7 \Omega$  Remarks: Switching times may increase for $V_{CE}$ (Clamp) $> 0.8 \cdot V_{CES}$ , higher $T_J$ or increased $R_G$	50	ns		
$t_{ri}$		240	ns		
$E_{on}$		3	mJ		
$t_{d(off)}$		280	ns		
$t_{fi}$		600	ns		
$E_{off}$		9.6	mJ		
$R_{thJC}$			0.42	K/W	
$R_{thCK}$		0.15		K/W	

## Reverse Diode (FRED)

## Characteristic Values

 $(T_J = 25^\circ\text{C}$ , unless otherwise specified)

Symbol	Test Conditions	min.	typ.	max.
$V_F$	$I_F = I_{C90}$ , $V_{GE} = 0 \text{ V}$ , Pulse test, $t \leq 300 \mu\text{s}$ , duty cycle $d \leq 2\%$		1.7	V
$I_{RM}$ $t_{rr}$	$I_F = I_{C90}$ , $V_{GE} = 0 \text{ V}$ , $-di_F/dt = 480 \text{ A}/\mu\text{s}$ $V_R = 360 \text{ V}$ $T_J = 125^\circ\text{C}$ $I_F = 1 \text{ A}$ ; $-di/dt = 200 \text{ A}/\mu\text{s}$ ; $V_R = 30 \text{ V}$ $T_J = 25^\circ\text{C}$	19	33	A
		175	ns	
		35	50	ns
$R_{thJC}$			0.75	K/W

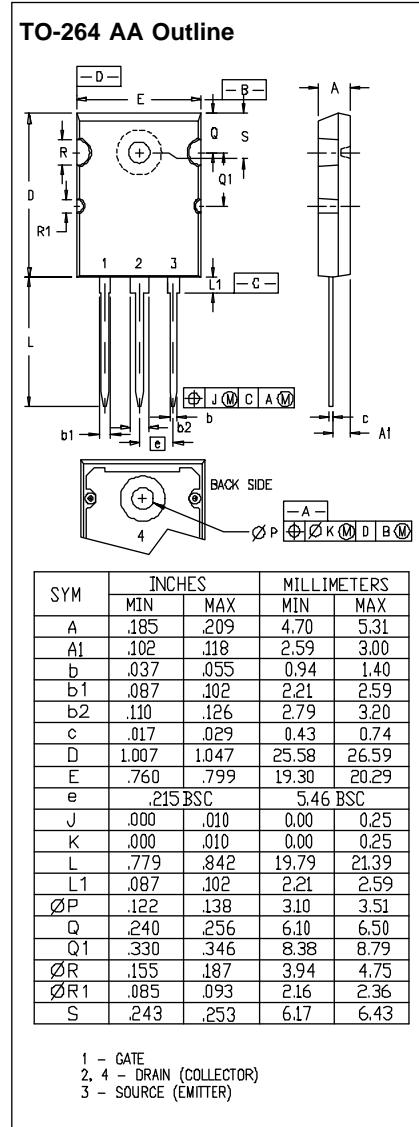


Fig. 1 Saturation Characteristics

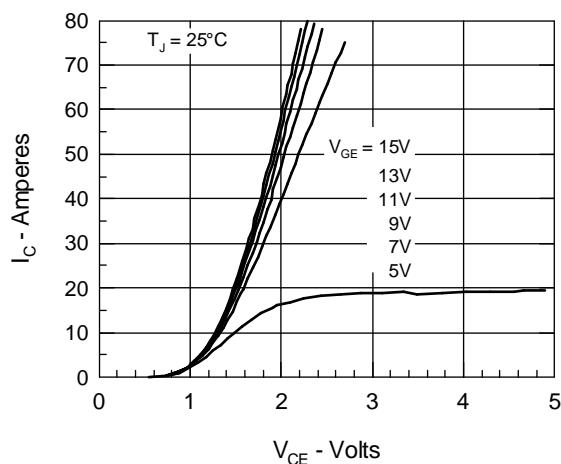


Fig. 3 Collector-Emitter Voltage vs. Gate-Emitter Voltage

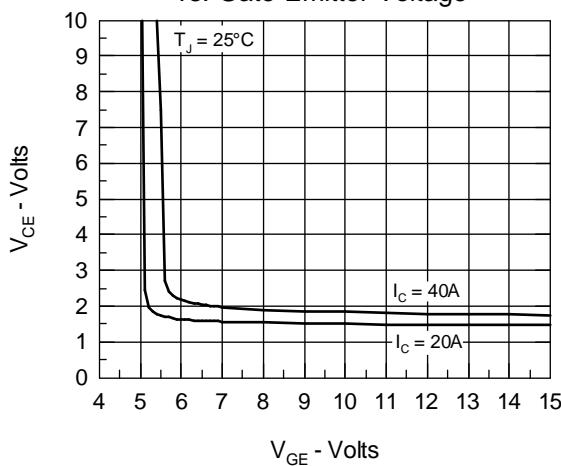


Fig. 5 Input Admittance

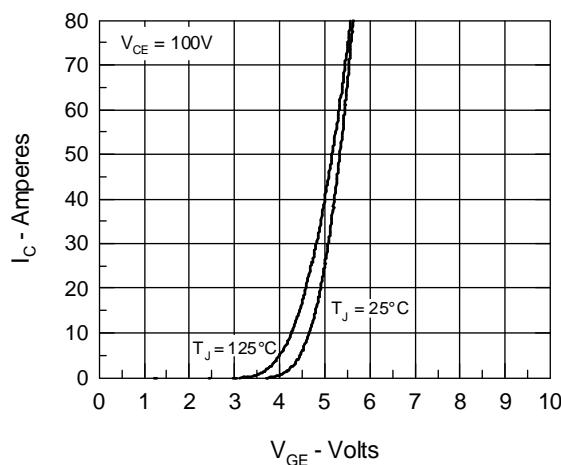


Fig. 2 Output Characteristics

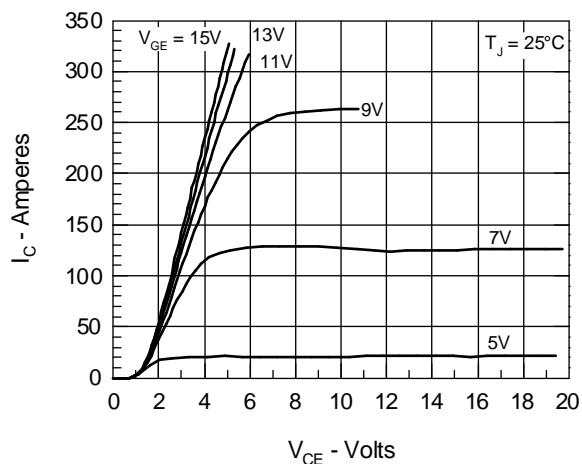


Fig. 4 Temperature Dependence of Output Saturation Voltage

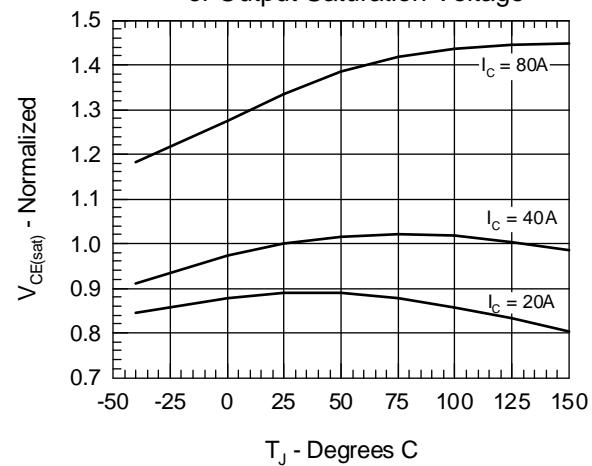


Fig. 6 Temperature Dependence of Breakdown and Threshold Voltage

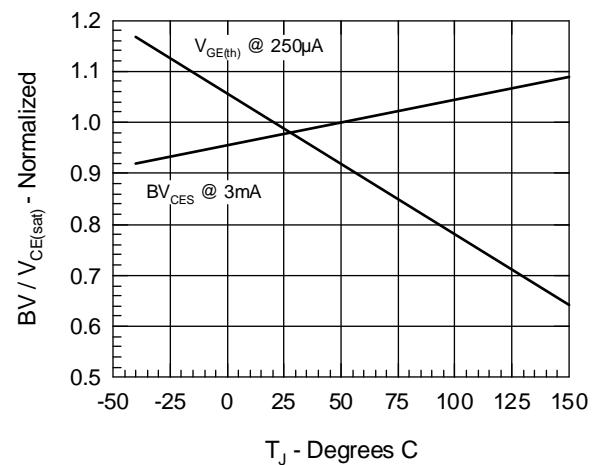


Fig.7 Gate Charge

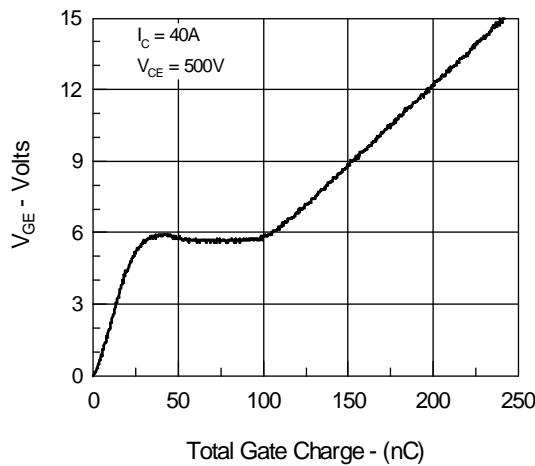


Fig.8 Turn-Off Safe Operating Area

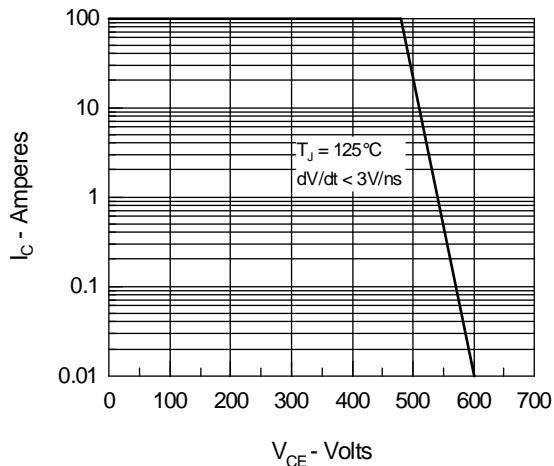


Fig.9 Capacitance Curves

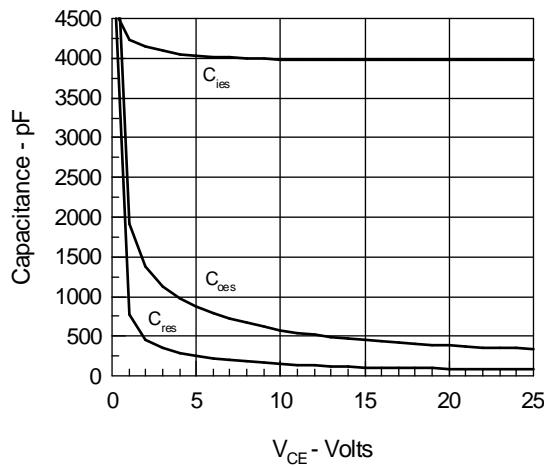
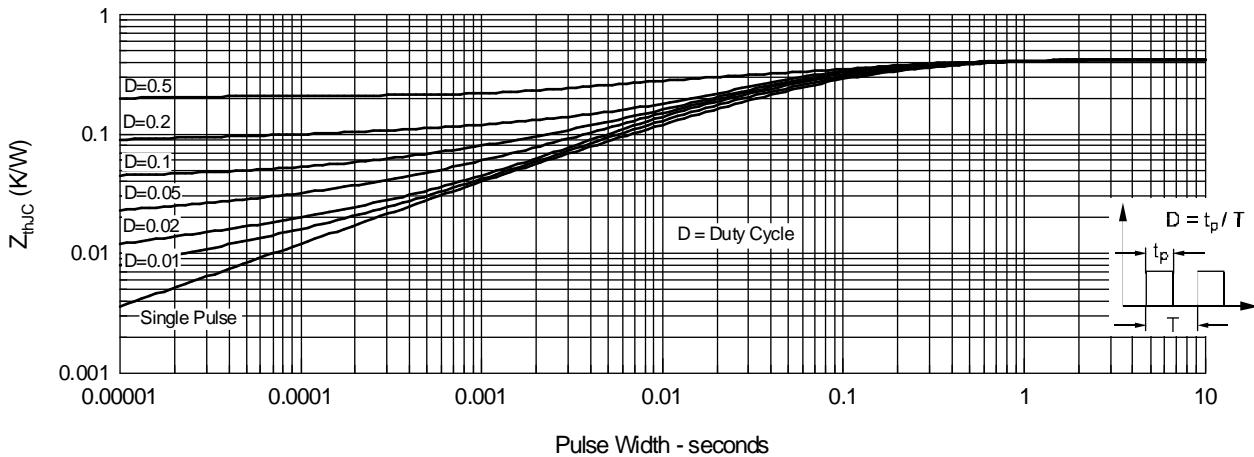


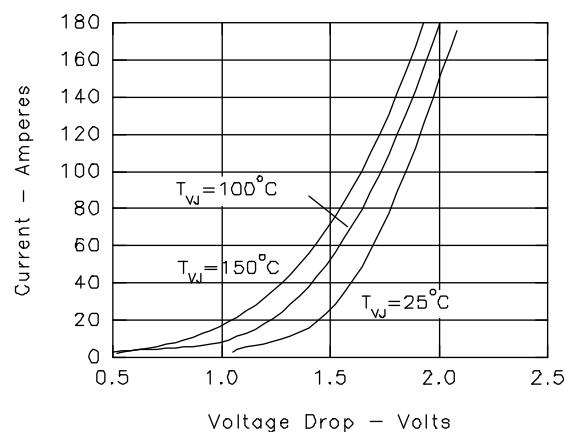
Fig.10 Transient Thermal Impedance



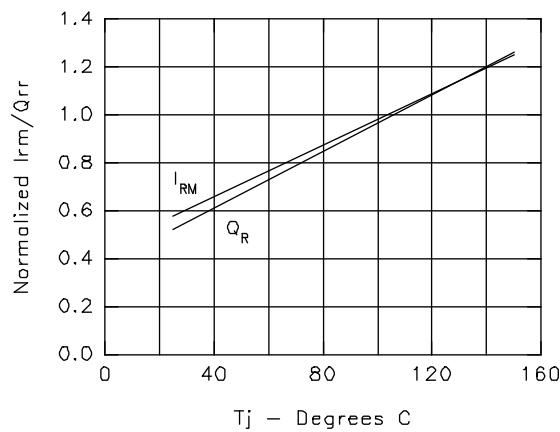
IXYS reserves the right to change limits, test conditions, and dimensions.

IXYS MOSFETs and IGBTs are covered by one or more of the following U.S. patents: 4,835,592 4,881,106 5,017,508 5,049,961 5,187,117 5,486,715  
4,850,072 4,931,844 5,034,796 5,063,307 5,237,481 5,381,025

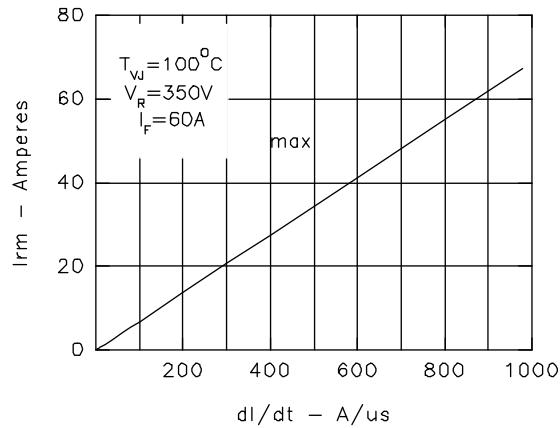
**Fig. 12. Maximum Forward Voltage Drop**



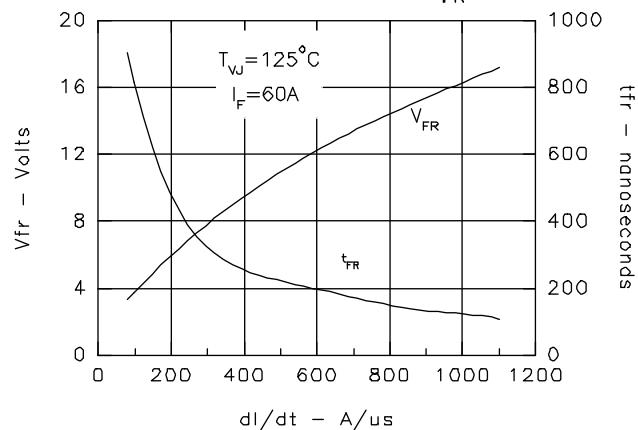
**Fig. 14. Junction Temperature Dependence of  $I_{RM}$  and  $Q_R$ .**



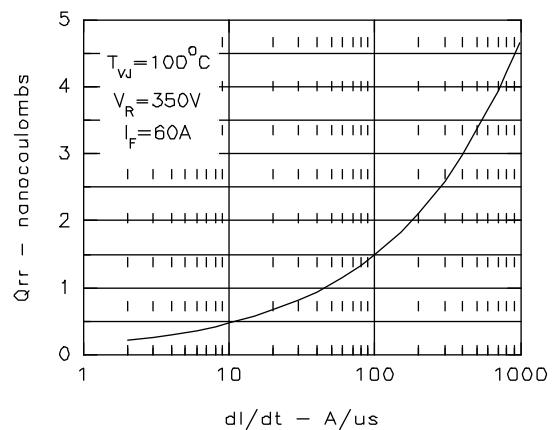
**Figure 16. Peak Reverse Recovery Current.**



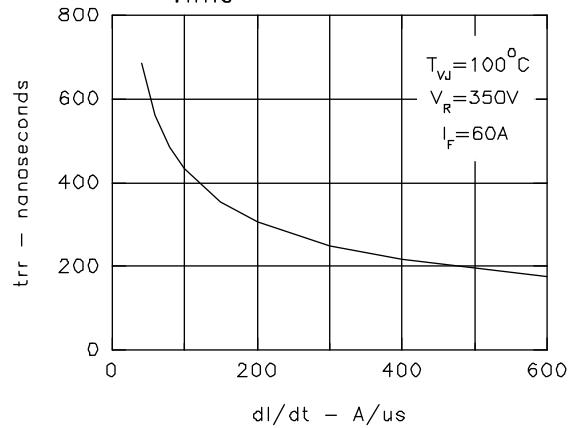
**Fig. 13. Peak Forward Voltage  $V_{FR}$  and Forward Recovery Time  $t_{FR}$ .**



**Fig. 15. Maximum Reverse Recovery Charge**



**Fig. 17. Maximum Reverse Recovery Time**



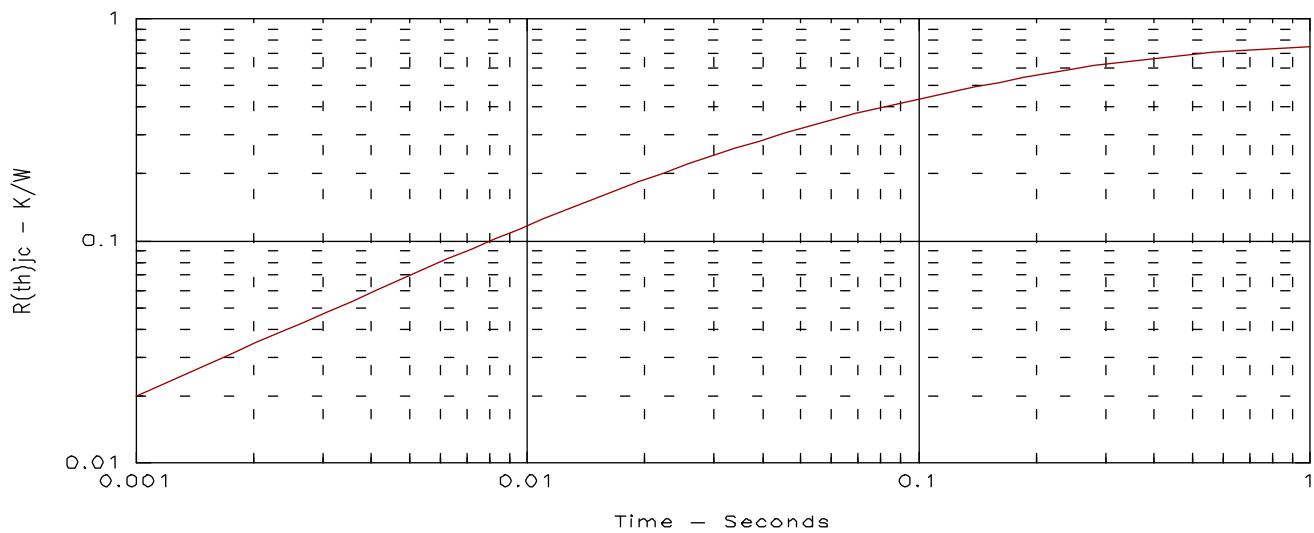


Fig. 18. Diode transient thermal resistance junction-to-case.